MOSFET – Power, Single, N-Channel, SO-8 FL 30 V, 75 A

Features

- Integrated Schottky Diode
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- CPU Power Delivery
- DC-DC Converters
- Low Side Switching

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	30	V
Gate-to-Source Vo	Gate-to-Source Voltage			±20	V
Continuous Drain Current R _{θJA}		T _A = 25°C	Ι _D	17.8	Α
(Note 1)		T _A = 85°C		12.9	
Power Dissipation $R_{\theta JA}$ (Note 1)		T _A = 25°C	P _D	2.70	W
Continuous Drain Current R _{θJA} ≤		T _A = 25°C	Ι _D	29.1	Α
10 sec		T _A = 85°C		21	
Power Dissipation $R_{\theta JA,} t \leq 10 \text{ sec}$	Steady	T _A = 25°C	P _D	7.18	W
Continuous Drain Current R _{BJA}	State	T _A = 25°C	Ι _D	10.4	Α
(Note 2)		T _A = 85°C		7.5	
Power Dissipation $R_{\theta JA}$ (Note 2)		T _A = 25°C	P _D	0.92	W
Continuous Drain Current R _{OJC}]	T _C = 25°C	Ι _D	75	Α
(Note 1)		T _C = 85°C		54	
Power Dissipation $R_{\theta JC}$ (Note 1)		T _C = 25°C	P _D	48	W
Pulsed Drain Current	t _p =10μs	T _A = 25°C	I _{DM}	188	Α
Current limited by package T _A = 25°C		I _{Dmaxpkg}	90	Α	
Operating Junction a Temperature	Operating Junction and Storage Temperature		T _J , T _{STG}	-55 to +150	°C
Source Current (Boo	Source Current (Body Diode)			46	Α
Drain to Source dV/dt			dV/dt	6	V/ns

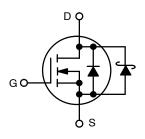


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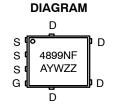
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V _{(BR)DSS} R _{DS(ON)} MAX		I _D MAX
30 V	5.0 mΩ @ 10 V	7F A
	7.5 mΩ @ 4.5 V	75 A

N-CHANNEL MOSFET







MARKING

A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping [†]		
NTMFS4899NFT1G	SO-8FL (Pb-Free)	1500 / Tape & Reel		
NTMFS4899NFT3G	SO-8FL (Pb-Free)	5000 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise stated)

Parameter	Symbol	Value	Unit
Single Pulse Drain-to-Source Avalanche Energy (V_{DD} = 50 V, V_{GS} = 10 V, I_L = 41 A_{pk} , L = 0.1 mH, R_G = 25 Ω)	EAS	84	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	TL	260	ŷ

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{ heta JC}$	2.6	
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	46.3	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{ heta JA}$	136.2	- C/VV
Junction-to-Ambient - t ≤ 10 sec	$R_{ heta JA}$	17.4	

- Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
 Surface-mounted on FR4 board using the minimum recommended pad size (50 mm², 1 oz Cu).

ELECTRICAL CHARACTERISTICS (T.I = 25°C unless otherwise specified)

Parameter	Symbol	Test Cond	lition	Min	Тур	Max	Unit
OFF CHARACTERISTICS				ı	I	I	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1.0 mA		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				27		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 24 V	T _J = 25 °C			500	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}	_S = ±20 V			±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 1.0 mA	1.5		2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				10		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A		3.9	5.0	
			I _D = 15 A		3.8		1
		V _{GS} = 4.5 V	I _D = 30 A		6.0	7.5	mΩ
			I _D = 15 A		5.8		
Forward Transconductance	9FS	V _{DS} = 1.5 V, I _D = 15 A			57		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				1600		
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V, f} = 1 \text{ MHz, V}_{DS} = 12 \text{ V}$			360		pF
Reverse Transfer Capacitance	C _{RSS}				165		1
Total Gate Charge	Q _{G(TOT)}				12.2		
Threshold Gate Charge	Q _{G(TH)}	\/ 45\/\/	15 \/· 20 A		1.6		
Gate-to-Source Charge	Q_{GS}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 15 \text{ V}; I_D = 30 \text{ A}$			4.6		nC
Gate-to-Drain Charge	Q_{GD}				4.6		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 15 V, I _D = 30 A			25		nC
SWITCHING CHARACTERISTICS (Note 4)							
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 15 \text{ V},$ $I_{D} = 15 \text{ A}, R_{G} = 3.0 \Omega$			12.6		
Rise Time	t _r				20.3		1
Turn-Off Delay Time	t _{d(OFF)}				20		ns
Fall Time	t _f				4.2		1

- 3. Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%.
- 4. Switching characteristics are independent of operating junction temperatures.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS (N	ote 4)			ı			
Turn-On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DS} = 15 V, I_{D} = 15 A, R_{G} = 3.0 Ω			8.8		ns
Rise Time	t _r				18.5		
Turn-Off Delay Time	t _{d(OFF)}				25.9		
Fall Time	t _f				2.5		
DRAIN-SOURCE DIODE CHARACT	ERISTICS						
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C		0.45	0.70	
		$V_{GS} = 0 V,$ $I_{S} = 2.0 A$	T _J = 125°C		0.43		V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 30 \text{ A}$			19		
Charge Time	t _a				9.2		ns
Discharge Time	t _b				9.8		
Reverse Recovery Charge	Q_{RR}				5.7		nC
PACKAGE PARASITIC VALUES							
Source Inductance	L _S	T _A = 25°C			0.38		nH
Drain Inductance	L _D				0.005		
Gate Inductance	L _G				1.84		
Gate Resistance	R_{G}				1.5	2.4	Ω

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

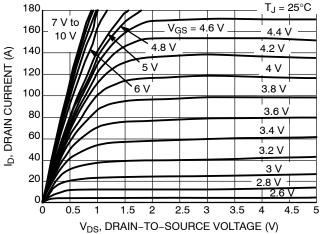


Figure 1. On–Region Characteristics

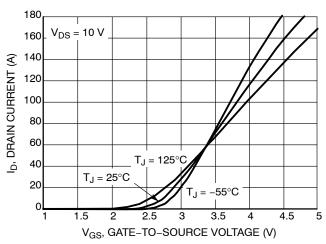


Figure 2. Transfer Characteristics

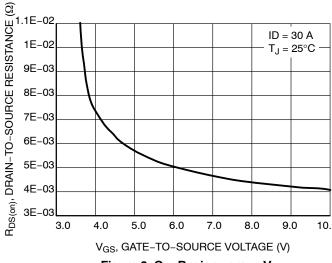


Figure 3. On-Region versus V_{GS}

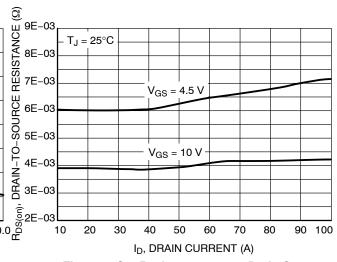


Figure 4. On-Resistance versus Drain Current and Gate Voltage

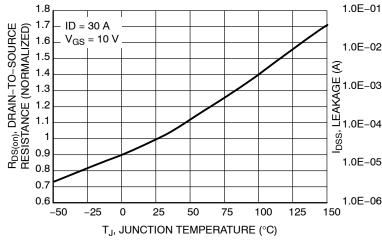


Figure 5. On–Resistance Variation with Temperature

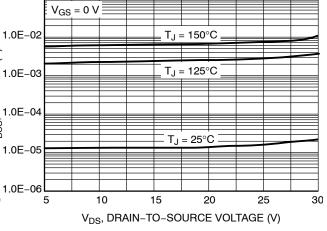


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

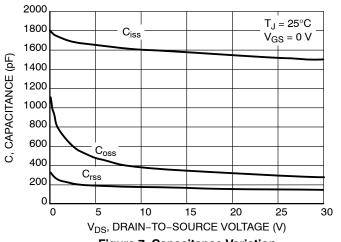


Figure 7. Capacitance Variation

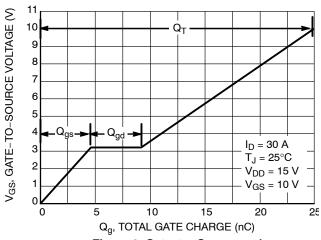


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

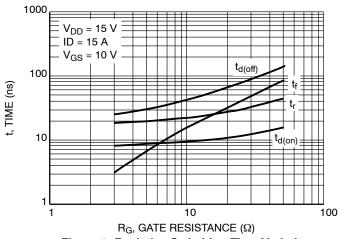


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

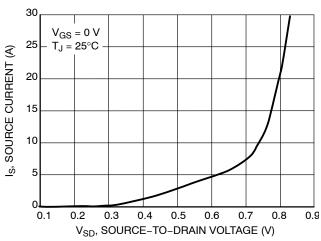


Figure 10. Diode Forward Voltage vs. Current

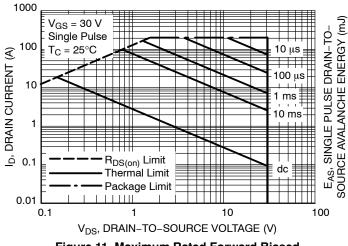


Figure 11. Maximum Rated Forward Biased Safe Operating Area

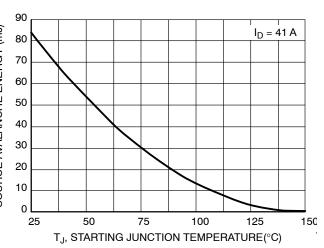


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

TYPICAL CHARACTERISTICS

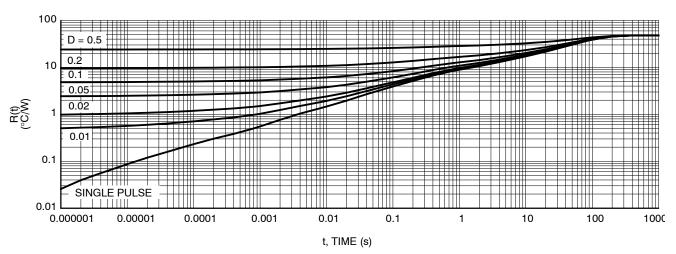


Figure 13. Thermal Response



0.10

SIDE VIEW

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

DATE 25 JUN 2018

NOTES:

BURRS

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE

	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	0.90	1.00	1.10		
A1	0.00		0.05		
b	0.33	0.41	0.51		
С	0.23	0.28	0.33		
D	5.00	5.15	5.30		
D1	4.70	4.90	5.10		
D2	3.80	4.00	4.20		
E	6.00	6.15	6.30		
E1	5.70	5.90	6.10		
E2	3.45	3.65	3.85		
е		1.27 BSC			
G	0.51	0.575	0.71		
K	1.20	1.35	1.50		
L	0.51	0.575	0.71		
L1	0.125 REF				
М	3.00	3.40	3.80		
θ	0 °		12 °		

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

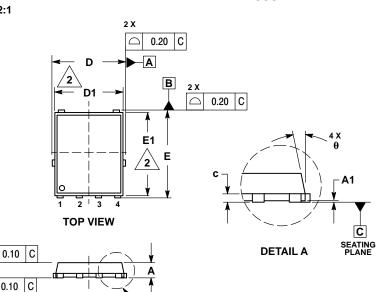
= Lot Traceability

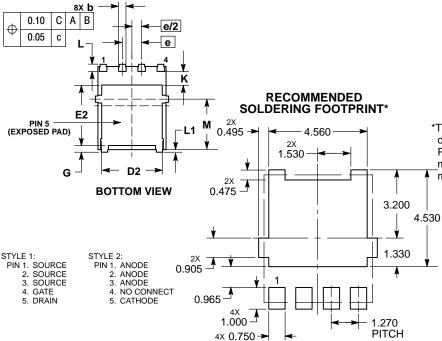
= Assembly Location Α

Υ = Year W = Work Week

ZZ

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.





DETAIL A

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIMENSIONS: MILLIMETERS

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